Remarks

Claims 1-9 remain in the application.

The Abstract of the Disclosure has been amended to eliminate reference numbers.

Consideration and allowance of the claims is respectfully requested.

Attached hereto is a marked up version of the changes made to the specification by the current amendment. The attached page is captioned "Version With Markings to Show Changes Made."

Respectfully submitted,

2-11-02
Date

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VERSION WITH MARKINGS TO SHOW CHANGES MADE

In The Abstract of the Disclosure

Please amend the Abstract of the Disclosure as follows:

A blade-like connecting needle for measuring a semiconductor wafer has an increased capability for measuring a small current and also has stable characteristics. The blade-like connecting needle [1] includes a blade signal [10] line for transmitting signal from the semiconductor wafer, a support insulator [8] covering at least a portion of the blade signal line [10], a plurality of blade guard patterns [12a, 12b, 12c, 12d] disposed in or on the support insulator [8] for electromagnetically shielding the blade signal line [10], and a probe [2] supported on the support insulator [8] and connected to the blade signal line [10]. There are also disclosed processes of producing the blade-like connecting needle [1]. A method for manufacturing a coaxial or hollow blade-like connecting needle is also provided.